



Product Change Notification

111014 - 03

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 111014 - 03
Change Title: Intel® Desktop Board DH61DL, Boxed and Bulk
PCN 111014-03, Product Material, Product Design
BIOS Update
Reason for Revision: Add text "for future processor support"
Date of Publication: April 06, 2012

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Feb 13, 2012
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Description of Change to the Customer:

Reason for Revision: Add text "for future processor support"

1. The BIOS will be updated from IN,BEH6110H.86A.0020 to IN,BEH6110H.86A.0038 **for future processor support**. To access the release notes or get a copy of the BIOS for evaluation, go to <http://downloadcenter.intel.com>.
2. The capacitor at location D3CE5 will be changed to a lower height version, which will improve CPU fan-sink installation margins.

Customer Impact of Change and Recommended Action:

It is recommended that customers evaluate this new BIOS to ensure a smooth transition. Intel validation of a new board revision does not include testing with older versions of BIOS. It has been observed that the change may report a "New device detected" in some operating systems. Microsoft* Windows will display a message and will not automatically install the necessary drivers; therefore customers need to update their OS image. This change is not expected to cause a change to the Microsoft Windows* operating system's software driver stack.

NOTE: New board revisions cannot be downgraded to an older BIOS version.

These changes have been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BOXDH61DLB3	915009	G14066-204	G14066-205
BLKDH61DLB3	915104	G14066-204	G14066-205
LADH61DLB3	915106	G14067-204	G14067-205

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
October 4, 2011	00	Originally Published PCN
January 27, 2012	01	BIOS Update
February 8, 2012	02	Capacitor Change
April 6, 2012	03	Add text "for future processor support"